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IR-1529 (2-1979)



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of  
Chuan Cheah et al.

Serial No.: 09/225,153

Filed: January 4, 1999

For: SEMICONDUCTOR PACKAGE

New York, New York

Date: April 19, 1999

Group Art Unit: 2811

Examiner: --

Assistant Commissioner for Patents  
Washington, D.C. 20231

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APR 28 1999

TECHNOLOGY CENTER 2800

PRELIMINARY AMENDMENT PURSUANT TO 37 C.F.R. §1.115

Sir:

Prior to examination of the above-identified  
application, please amend the application as follows:

IN THE SPECIFICATION:

Page 5, line 23, after "of" insert --an  
alternative embodiment  
of--;

after line 24, insert --Fig. 4a-4c are  
perspective views of the  
semiconductor package of  
Fig. 4--;

Page 7, line 9, after "18." insert --Soft  
solder may also be used--.  
line 26, after "12b." insert --Figs.  
4a-4c are perspective views  
of the package of Fig. 4---.

IN THE DRAWING:

The Examiner is requested to review and approve  
proposed new Figs. 4a, 4b, and 4c. These new figures show